

07-19-2006

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ORIGINAL DOCUMENTS OR COPY THEREOF.

( OFFICE. PLEASE RECORD THE ATTACHED

## 1. Name of conveying parties:

- (a) KIM, Sang-Gab (b) LEE, Wo-Geun  
(c) KIM, Shi-Yul (d) JU, Jin-Ho  
(e) KIM, Jang-Soo (f) WHANGBO, Sang-Woo  
(g) OH, Min-Seok (h) RYU, Hye-Young  
(i) CHIN, Hong-Kee

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

## 2. Name and address of receiving party:

Name: SAMSUNG ELECTRONICS CO., LTD.

Address: 416, Maetan-dong, Yeongtong-gu, Suwon-si,  
Gyeonggi-do, Korea

Additional name(s) of receiving party(ies) attached?

☐ Yes ☒ No113261 U.S. PTO  
11/486330

071206

## 3. Nature of Conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other \_\_\_\_\_

Execution Date: June 13, 2006

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: June 13, 2006

## A. Patent Application No.(s)

Title: THIN FILM TRANSISTOR ARRAY  
PANEL AND FABRICATION

## B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Howard R. Popper  
Internal Address: MACPHERSON, KWOK CHEN & HEID LLP  
Street Address: 1762 Technology Drive, Suite 226  
City San Jose State CA Zip 95110

## 6. Total number of applications and patents involved: One (1)

## 7. Total fee (37 CFR 3.41): \$40.00

- ☒ Authorized to be charged to Deposit Account No. 50-2257.  
☒ Charge Deposit Account No. 50-2257 for any additional fees required for this conveyance and credit Deposit Account No. 50-2257 any amounts overpaid

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## 8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David W. Heid, Reg. No. 25,875  
Name of Person Signing

*David W. Heid*  
Signature

July 12, 2006  
Date

Total number of pages comprising cover sheet: 5

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PATENT

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**ASSIGNMENT**

For good and valuable consideration, receipt of which is hereby acknowledged, we

<b>KIM, Sang-Gab</b>	of	<b>301-306 Samik apt., 15 Myeongil-dong, Gangdong-gu, Seoul, Korea</b>
<b>LEE, Woo-Geun</b>	of	<b>102-504 Hyundai Morning Side 2-cha apt., Bora-ri, Giheung-eup, Yongin-si, Gyeonggi-do, Korea</b>
<b>KIM, Shi-Yul</b>	of	<b>806-1601 Manhyeonmaeul 8-danji, Doosan We've apt., 861 Sanghyeon-dong, Yongin-si, Gyeonggi-do, Korea</b>
<b>JU, Jin-Ho</b>	of	<b>105-504 Mapo Samsung apt. Dohwa 1-dong, Mapo-ku, Seoul, Korea</b>
<b>KIM, Jang-Soo</b>	of	<b>643-1703 Sinnamusil 6-danji Sinwon apt., Yeongtong-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea</b>
<b>WHANGBO, Sang-Woo</b>	of	<b>7-704 Asia Athlete's apt., Jamsil 7-dong, Songpa-gu, Seoul, Korea</b>
<b>OH, Min-Seok</b>	of	<b>102-202 Hanil apt., Sinbong-dong, Yongin-si, Gyeonggi-do, Korea</b>
<b>RYU, Hye-Young</b>	of	<b>16-96 Jeongreung 1-dong, Seongbuk-gu, Seoul, Korea</b>
<b>CHIN, Hong-Kee</b>	of	<b>147-201 Hanil Town, Jowon-dong, Jangan-gu, Suwon-si, Gyeonggi-do, Korea</b>

hereby sell, assign and transfer to SAMSUNG ELECTRONICS CO., LTD., a corporation, having a place of business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea, its successors and assigns, the entire right, title and interest throughout the world in our invention in

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for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.


Executed this 13th day of June, 2006.

*KIM SANG GAB*

**KIM, Sang-Gab**

WITNESSED:

Signature



Date:

13/06/2006

KIM, You-Mi

Executed this 13<sup>th</sup> day of June, 2006.



**LEE, Woo-Geun**

WITNESSED:

Signature


Lee Kyung - A

Date:

13/06/2006

LEE, Kyung-A

Executed this 13<sup>th</sup> day of June, 2006.



**KIM, Shi-Yul**

WITNESSED:

Signature



Date:

13/06/2006

KIM, You-Mi

Executed this 13<sup>th</sup> day of June, 2006.

Ju Jin-Ho

**JU, Jin-Ho**

WITNESSED:

Signature



Date:

13/06/2006

**PARK, Mi-Young**

Executed this 13<sup>th</sup> day of June, 2006.

Kim, Jang-Soo

**KIM, Jang-Soo**

WITNESSED:

Signature

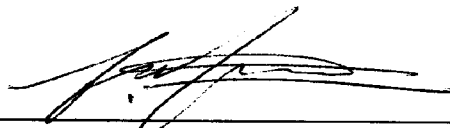


Date:

13/06/2006

**PARK, Mi-Young**

Executed this 13<sup>th</sup> day of June, 2006.



**WHANGBO, Sang-Woo**

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Lee Kyung - A

Date:

13/06/2006

**LEE, Kyung-A**

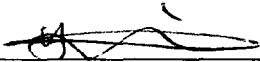
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Oh Min Seok

**OH, Min-Seok**

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Signature



Date:

13/06/2006

KIM, You-Mi

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Ryu, Hye-Young

**RYU, Hye-Young**

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Signature

Lee Kyung - A

Date:

13/06/2006

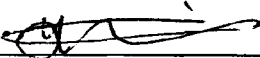
LEE, Kyung-A

Executed this 13th day of June, 2006.

  
**CHIN, Hong-Kee**

WITNESSED:

Signature



Date:

13/06/2006

KIM, You-Mi